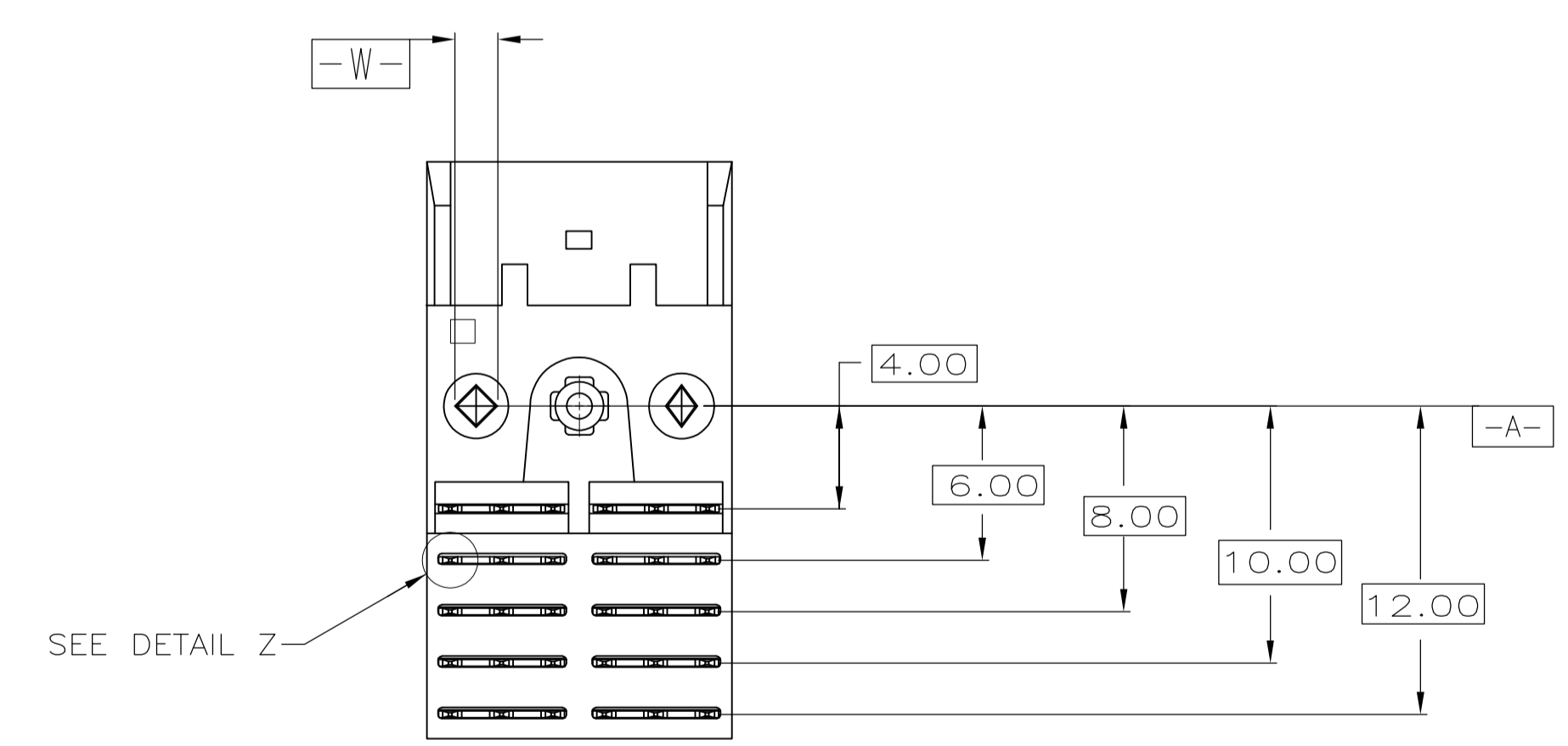
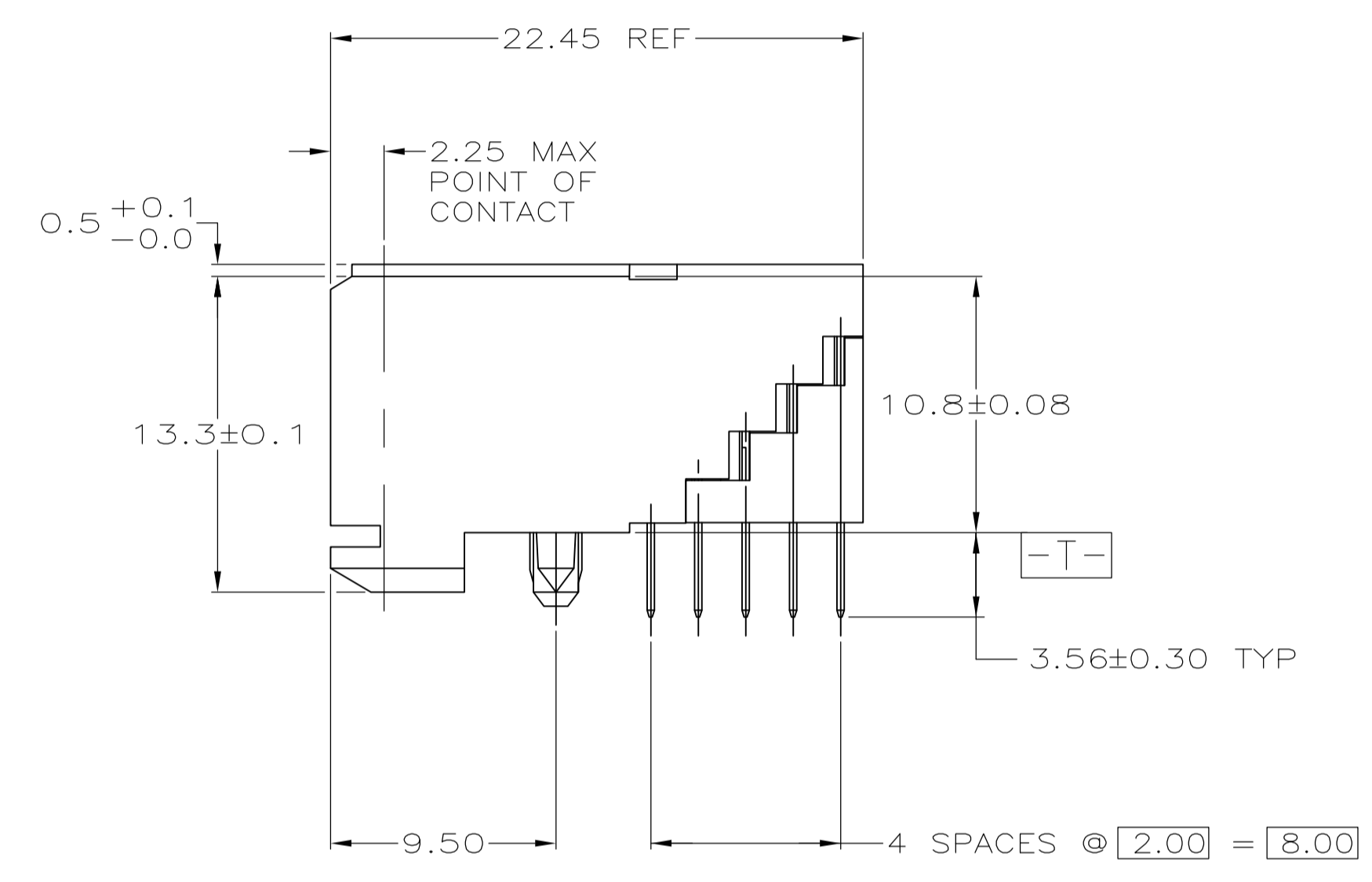
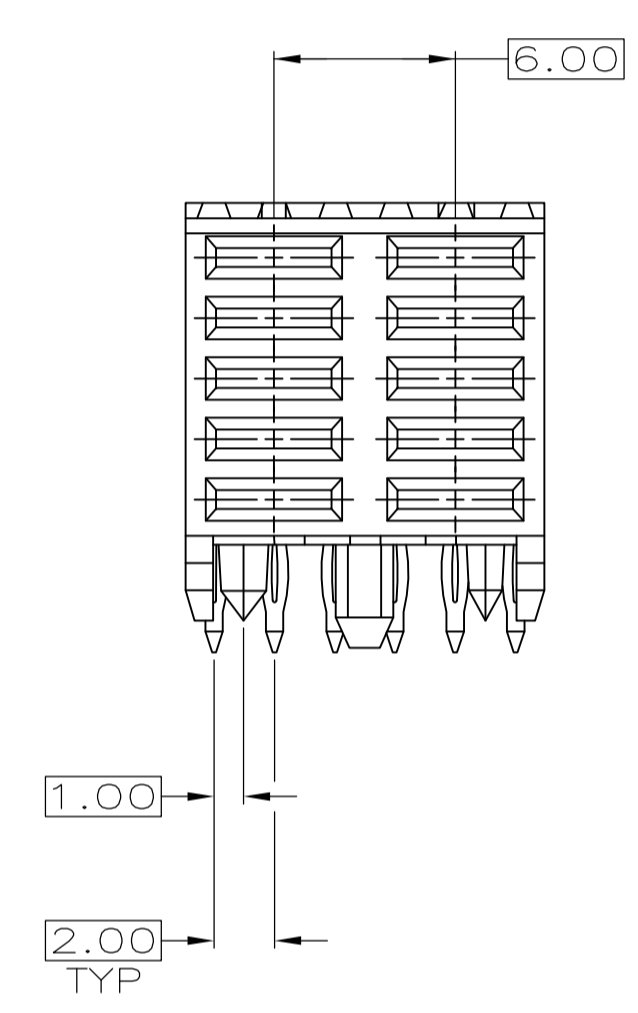
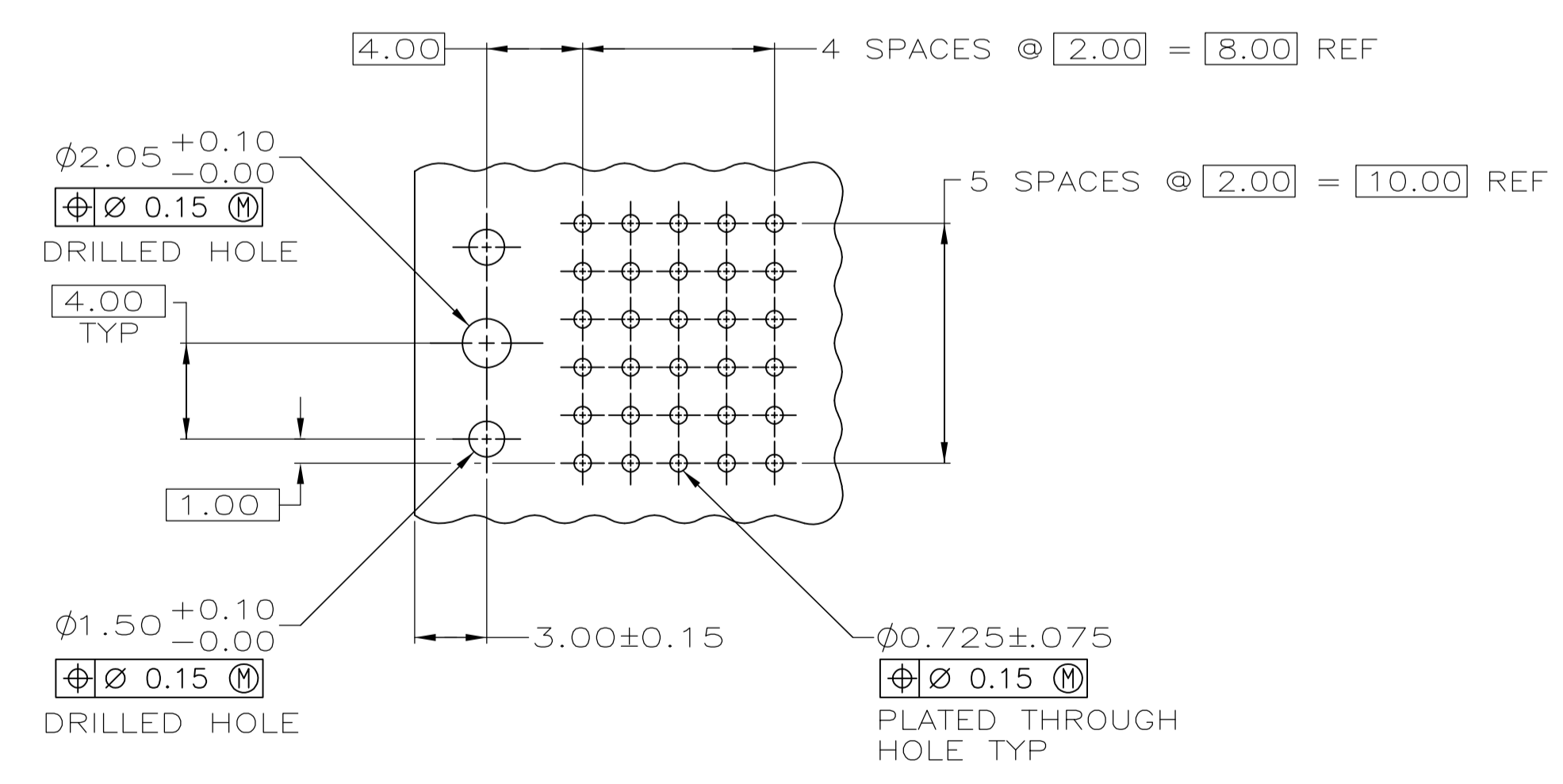


DETAIL Z  
SCALE 20:1

- ① HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.
- ② CONTACT MATERIAL: COPPER ALLOY
- ③ CONTACT FINISH:  
 UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
 ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
 ON LEADS:  
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.  
 LUBRICATION (MIN MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



SEE DETAIL Z



RECOMMENDED CURCUIT PATTERN  
PER IPC-D300 TYPE II, CLASS C  
(COMPONENT SIDE)

③	536676-1
FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN 5-29-98		Tyco Electronics Corporation	
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED:		R/A,5 ROW,10 POSN,W/TAIL ORGANIZER	
0 PLC	± -	1 PLC	± -	2 PLC	± 0.13
3 PLC	± -	4 PLC	± -	ANGLES	± -
MATERIAL	① ② ③	FINISH	③	WEIGHT	-
CUSTOMER DRAWING				SCALE: 4:1	SHEET 1 OF 1

**OBSELETE**  
**NOT the LATEST REVISION**

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)